

Amendments to the Specification:

Please replace the paragraph, beginning at page 2, line 1, with the following rewritten paragraph:

As shown in Fig. 2, however, in the case of the chip resistor disclosed in the Japanese Patent Laid-open Publication No. H01-42102 (S64-42102), when a slit 4 is not provided, a resistor element 3 becomes shorter. On the other hand, when a plurality of slits 4 are provided, the resistor element 3 becomes thinner, and is changed in resistive property by heat applied during the laser trimming processes, lowering its surge property. Conventionally, during the laser trimming, the resistor element 3, along with a substrate 1, is cut to form a groove that reaches under a surface of the substrate and has a bottom lower than the surface. Formation of five slits 4 by laser increases man-hours, thus productivity decrease.